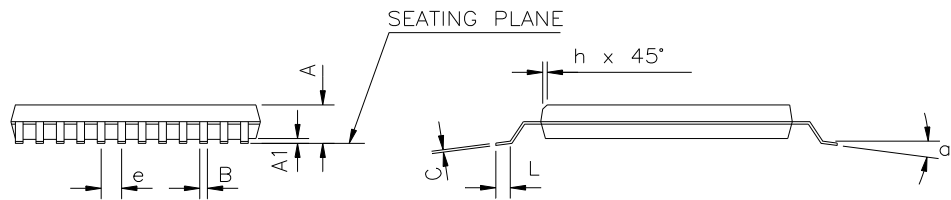
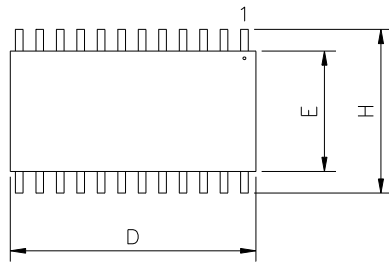


150 MIL VSOP
 VERY SMALL OUTLINE PACKAGE(VSOP)

PACKAGE INFORMATION

NOTES

1. LEAD WIDTH AND LEAD THICKNESS EXCLUSIVE OF SOLDER PLATE
2. PACKAGE OUTLINE EXCLUSIVE OF MOLD FLASHES AND BURR DIMENSIONS
3. ALLOWABLE MOLD FLASH IS 5 MILS PER SIDE.
4. DIMENSIONS ARE GIVEN IN INCHES.
5. LEAD COPLANARITY IS 0.003 INCH MAX.



JEDEC #	MO-154BB		MO-154AB	
	TYPE	40 LEAD	48 LEAD	
SYMBOL	Min	Max	Min	Max
A	0.059	0.069	0.059	0.069
A1	0.004	0.008	0.004	0.008
B	0.0067	0.009	0.0051	0.008
C	0.0075	0.0098	0.0075	0.0098
D	0.386	0.394	0.386	0.394
E	0.150	0.157	0.150	0.157
e	0.0197 BSC 0.5mm		0.0157 BSC 0.4mm	
H	0.228	0.244	0.228	0.244
h	0.010	0.016	0.010	0.016
L	0.020	0.030	0.024	0.029
α°	0°	8°	0°	8°

PREPARED BY	NK	REF. NO. DIM-VSOP-01	REV. NO.	SPEL SEMICONDUCTOR LIMITED INDIA
CHECKED BY	SP		1	
APPROVED BY	NJC		DATE 01.07.01	

